

Notes:

- ① Material: UL recognized component 370HR, UL File Number: E41625, relative permittivity 4.2 nominal
- ② Controlled impedance of 90 Ohm for the USB and MIPI CSI-2 interface differential data signals should be carried out. The impedance of particular traces has been designed using exactly Isola 370HR material performance data. Usage of any replacement material is not recommended.
- ③ Controlled impedance of 50 Ohm for the internal antenna trace within the RSL10 SiP IC should be carried out. The impedance of particular trace has been designed using exactly Isola 370HR material performance data. Usage of any replacement material is not recommended.
- ④ Finish: ENIG (Electroless Nickel Immersion Gold), nickel layer $1 \div 4 \mu\text{m}$, gold layer $0.076 \div 0.2 \mu\text{m}$
- ⑤ All vias in SMD pads have to be filled and plated over to allow proper soldering
- ⑥ All gerber files generated as a top view
- ⑦ Gerber files for internal power planes have to be inverted
8. Fabricate according IPC-A-600
9. Non-conductive epoxy ink recommended for silkscreen
10. Silkscreen should not cover any exposed copper, silkscreen gerber data have to be trimmed eventually
11. All holes diameter refer to final diameter after eventual plating
12. Solder mask tenting is applied on number of vias both on top layer

Gerber file extensions table

Gerber files	
.GTO	Top side silkscreen
.GTP	Top side solder paste mask
.GTS	Top side solder mask
.GTL	Top layer L1_TOP
.G1	Internal signal layer/ground plane L2_GND
.GP1	Internal power plane L3_PWR - has to be inverted
.GBL	Bottom layer L4_BOTTOM
.GBS	Bottom side solder mask
.GBP	Bottom side solder paste mask
.GBO	Bottom side silkscreen
.GBP	Bottom side solder paste mask
.GM1	Board outline

Drill file extensions table

Drill files	
ULP_BLE_Camera-RoundHoles.TXT	Layer pair L1_TOP to L4_BOTTOM - round holes
ULP_BLE_Camera-SlotHoles.TXT	Layer pair L1_TOP to L4_BOTTOM - slot holes
ULP_BLE_Camera-RoundHoles.TXT1	Layer pair L1_TOP to L2_GND - round holes

SECO-RSL10-CAM-COLOR-GEVK**Revision:**
rev0.3**State:**
released*PCB fabrication notes and requirements*

Engineer: T. Duris

Date: 18. March 2021

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Layer Stack

	Material	Layer	Thickness	Dielectric Material	Permittivity	Type	Gerber
		Top Paste				Paste Mask	GTP
		Top Overlay				Legend	GTO
	Surface Material	Top Solder	0.0150mm(0.591mil)	Solder Resist		Solder Mask	GTS
	Copper	L1_TOP	0.0430mm(1.693mil)			Signal	GTL
	Prepreg		0.0810mm(3.189mil)	Isola 370HR: 1080-68	3.86	Dielectric	
	Copper	L2_GND	0.0180mm(0.709mil)			Signal	G1
	Core		1.0670mm(42.008mil)	Isola 370HR: 6x7628-42	4.36	Dielectric	
	Copper	L3_PWR	0.0180mm(0.709mil)			Internal Plane	GP1
	Prepreg		0.0810mm(3.189mil)	Isola 370HR: 1080-68	4.2	Dielectric	
	Copper	L4_BOTTOM	0.0430mm(1.693mil)			Signal	GBL
	Surface Material	Bottom Solder	0.0150mm(0.591mil)	Solder Resist		Solder Mask	GBS
		Bottom Overlay				Legend	GBO
		Bottom Paste				Paste Mask	GBP
Total thickness: 1.3810mm(54.372mil)							

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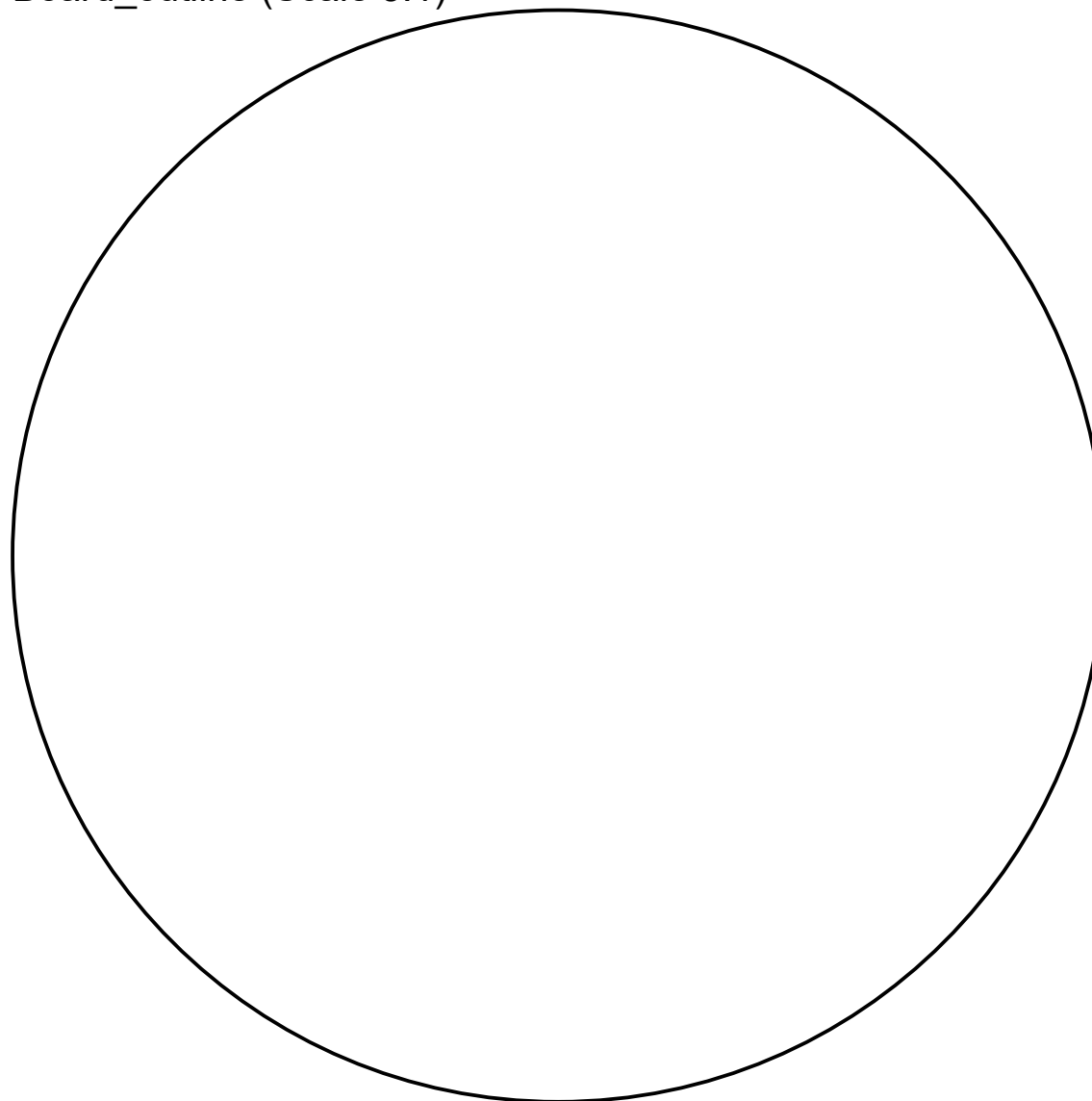
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Board_outline (Scale 3:1)

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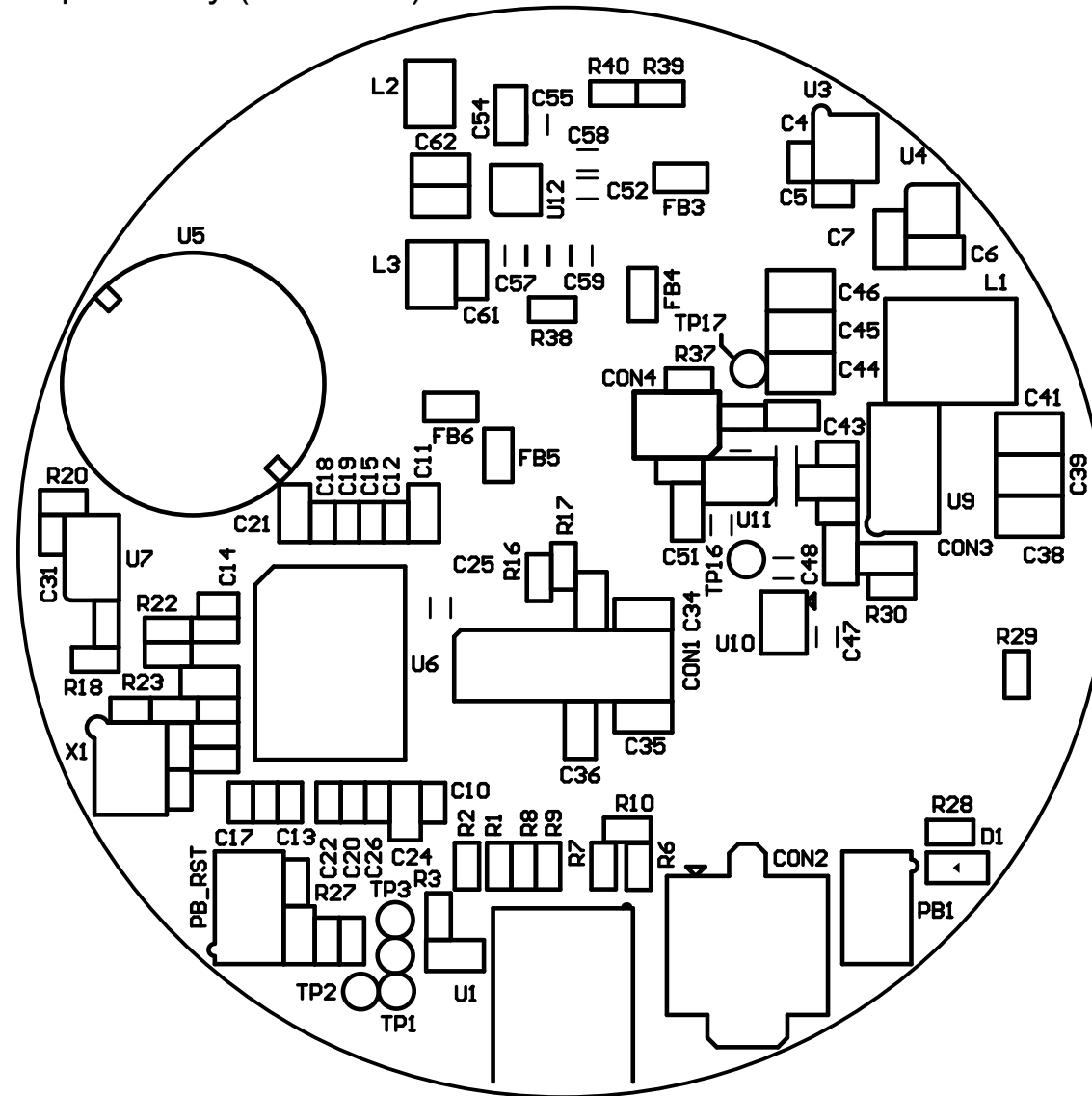
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Top Overlay (Scale 3:1)



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Top side silkscreen

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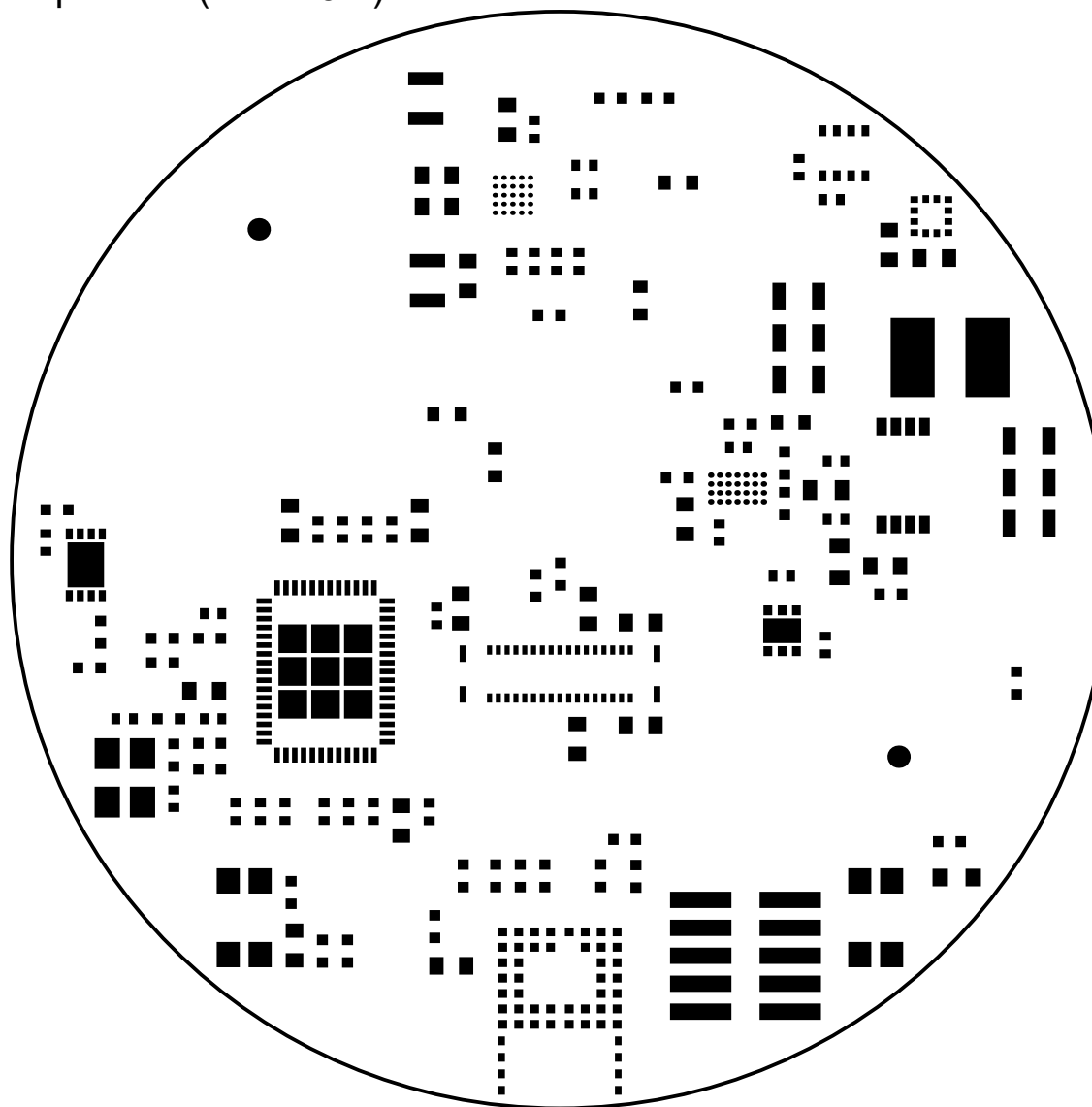
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Top Paste (Scale 3:1)

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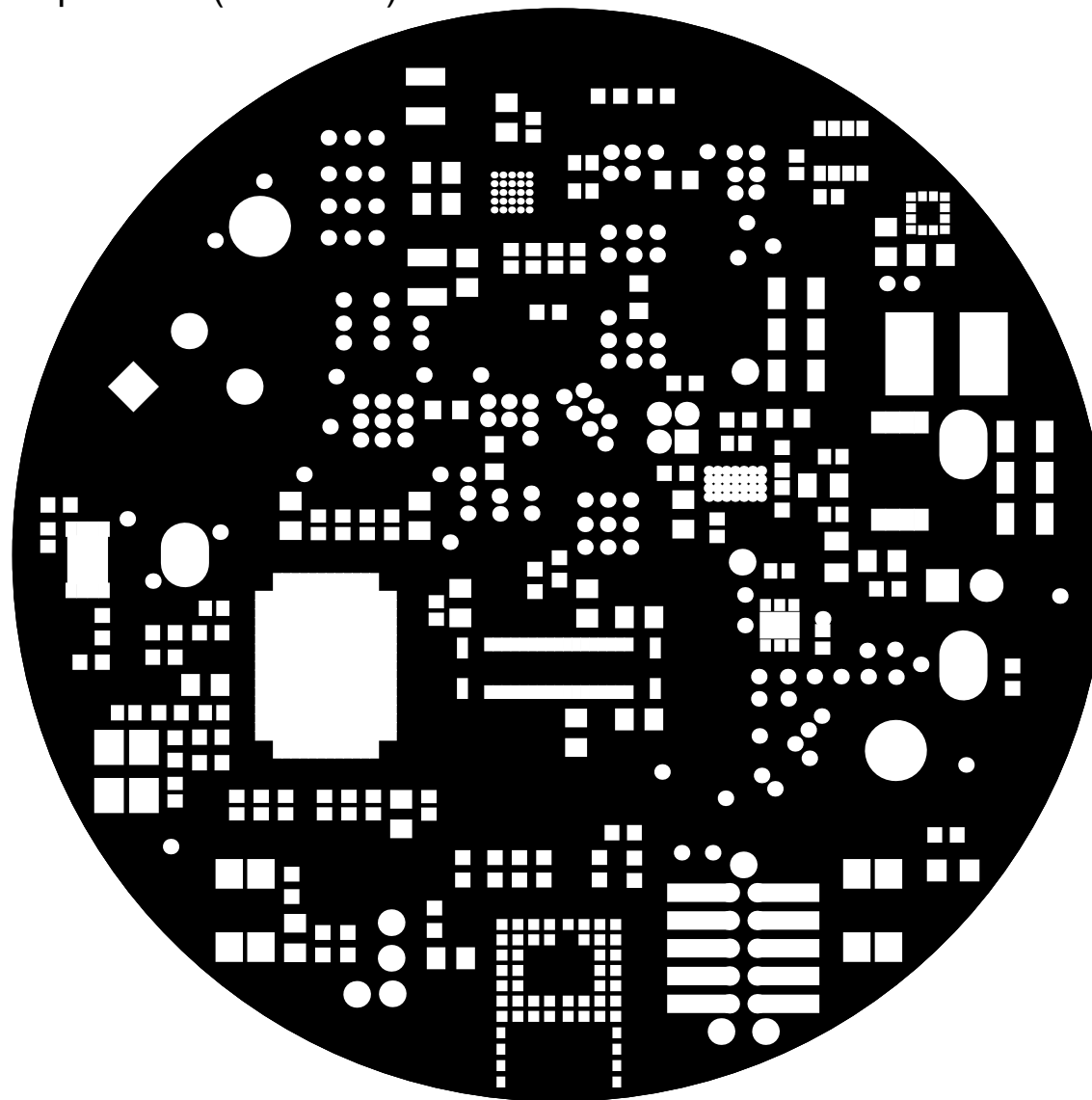
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Top Solder (Scale 3:1)

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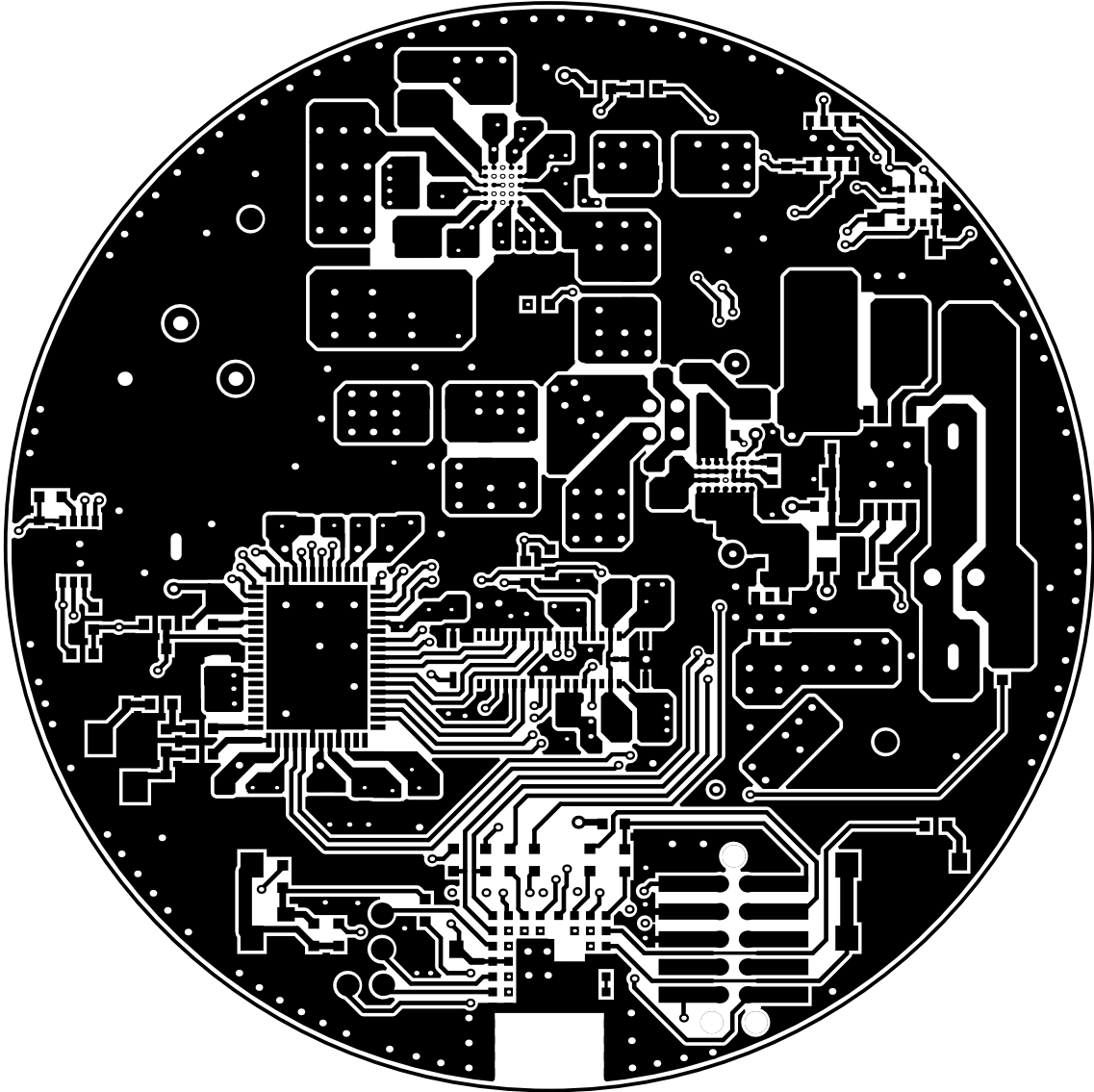
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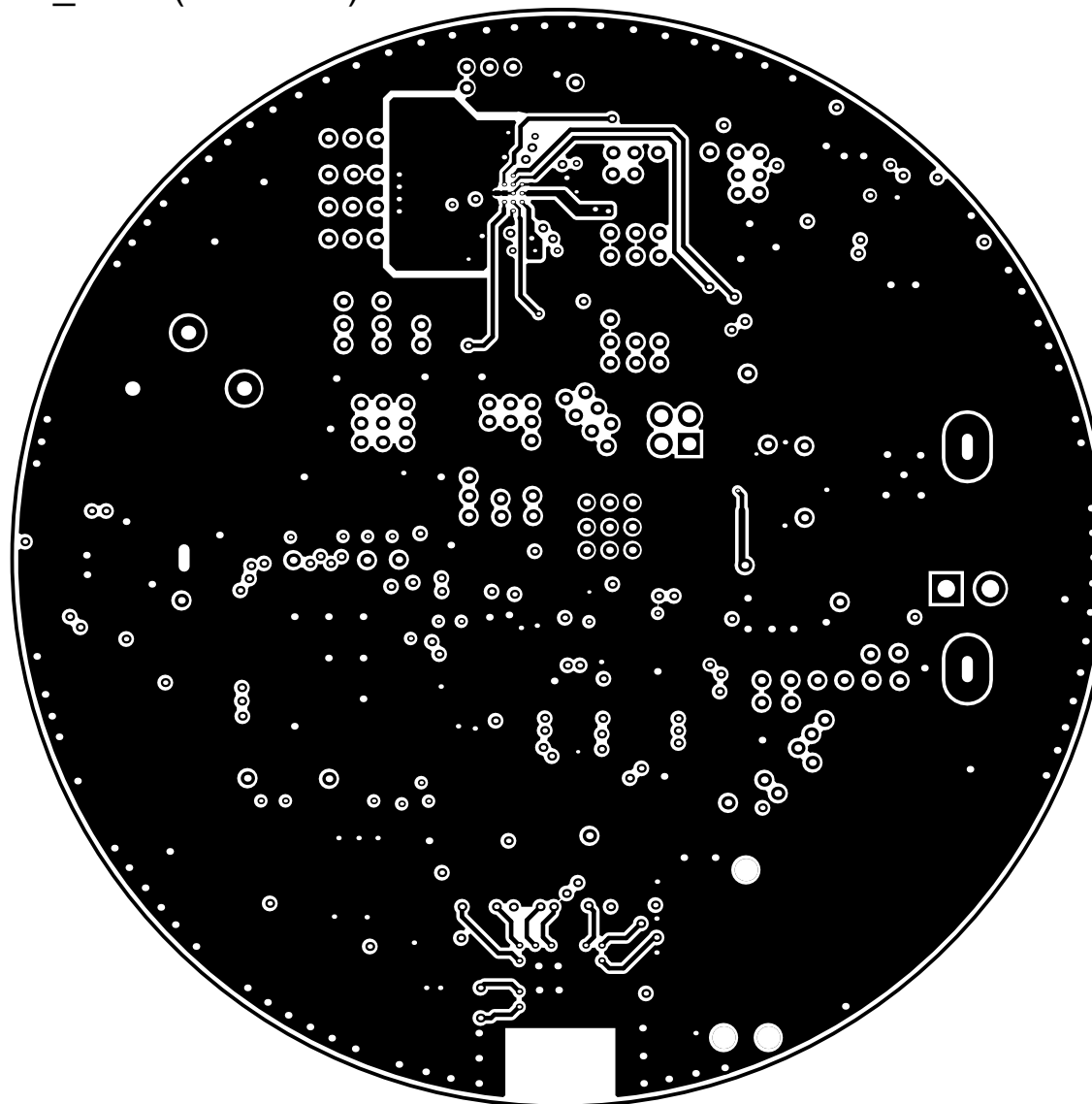
L1_TOP (Scale =3:1)



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Layer L1_TOP		Fabrication document	Sheet 7 / 15
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L2_GND (Scale 3:1)



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Internal signal layer/ground plane L2_GND

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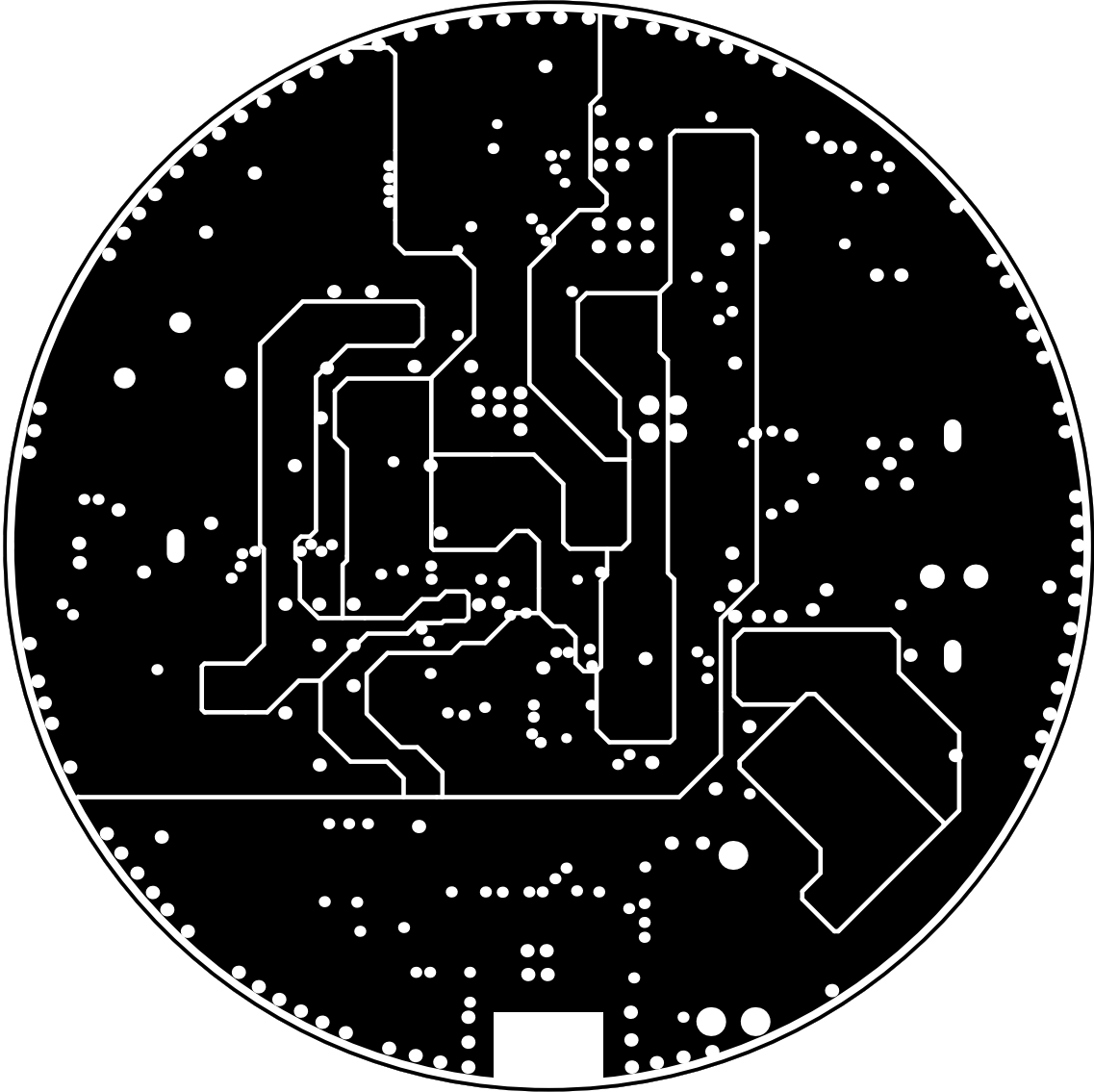
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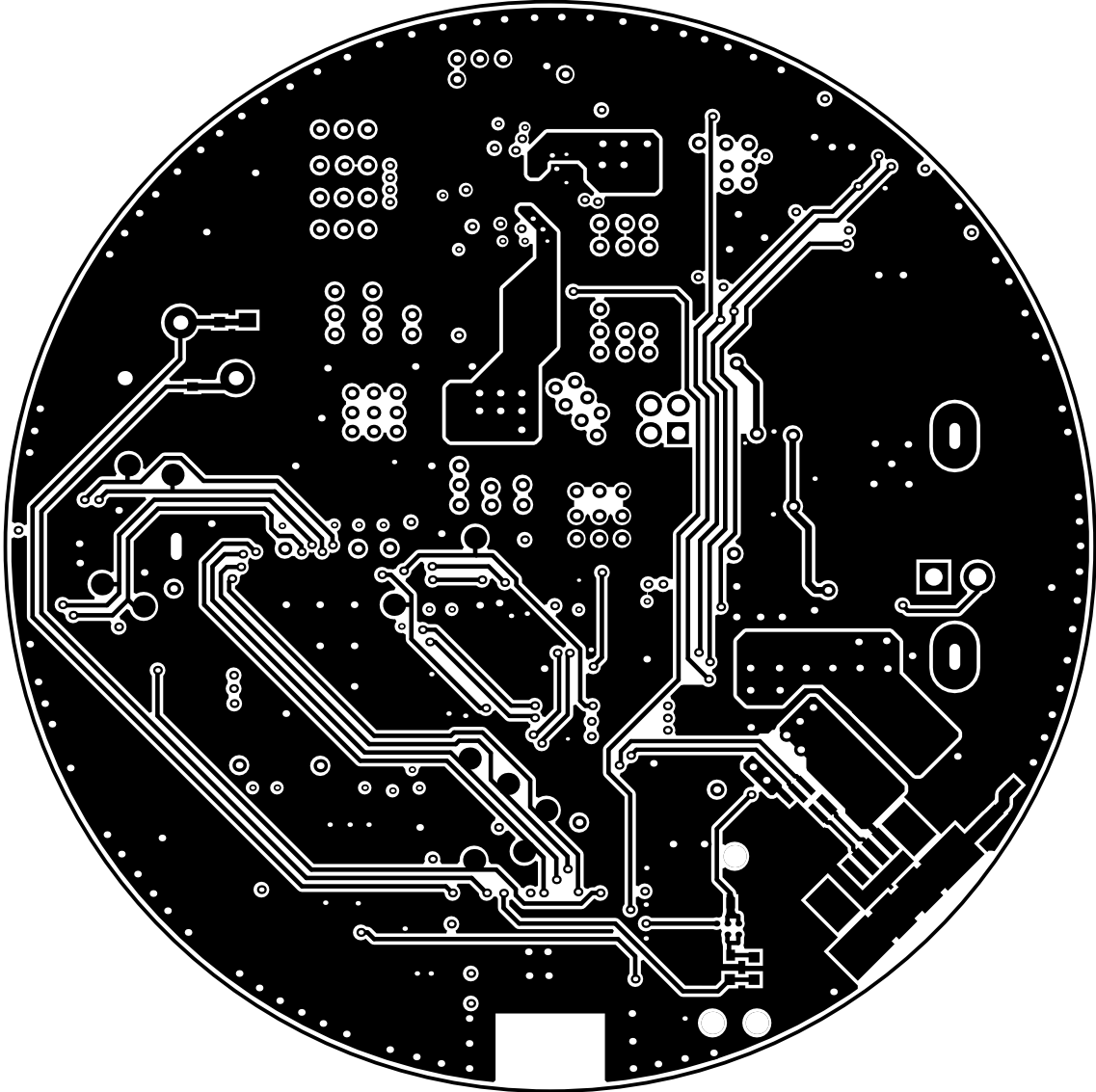
L3_PWR (Scale 3:1)




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Internal power plane L3_PWR		Fabrication document	Sheet 9 / 15
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L4_BOTTOM (Scale 3:1)



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Layer L4_BOTTOM		Fabrication document	Sheet 10 / 15
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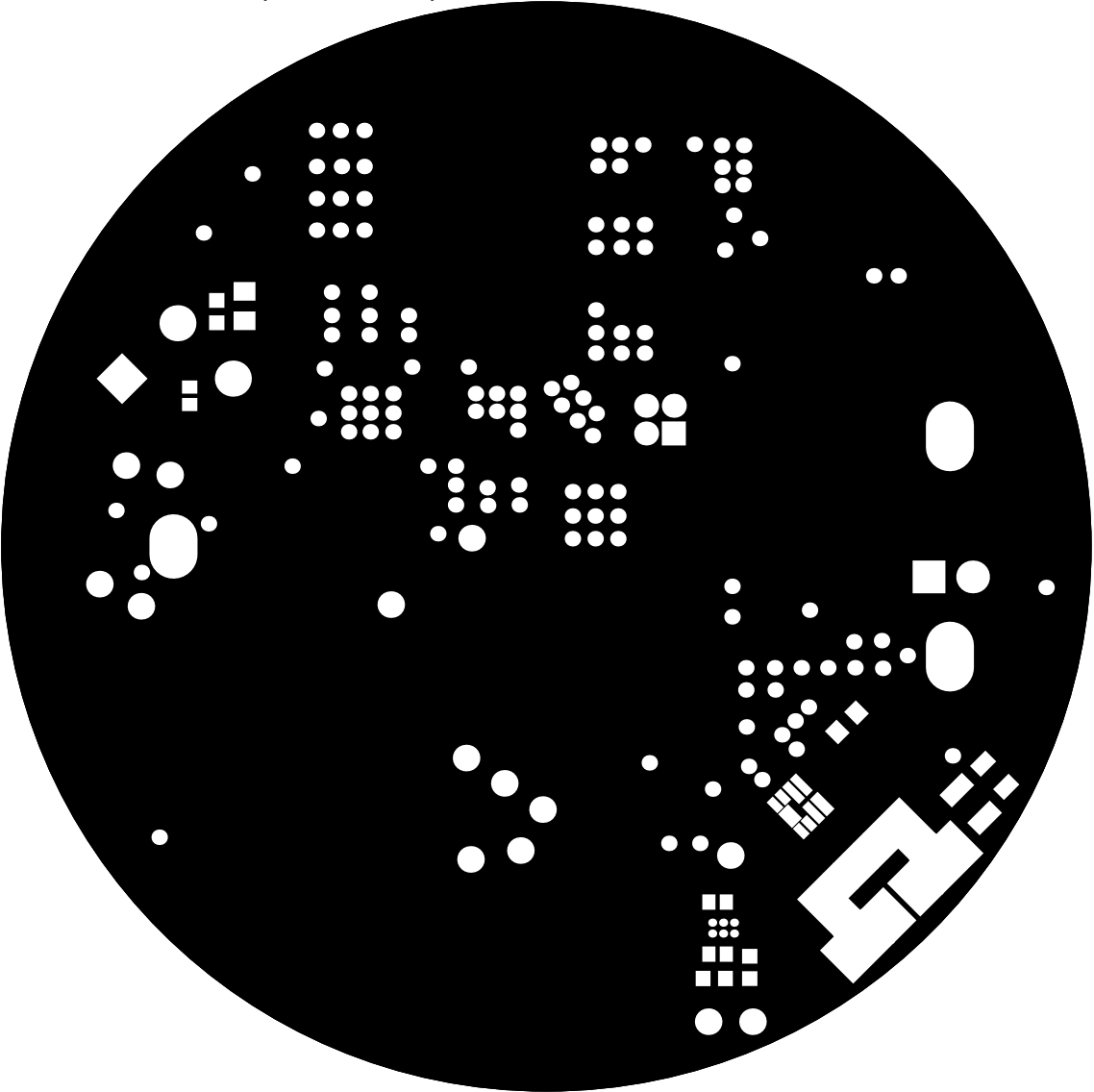
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Bottom Solder (Scale 3:1)



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<i>Bottom side solder mask</i>		Fabrication document	Sheet 11 / 15
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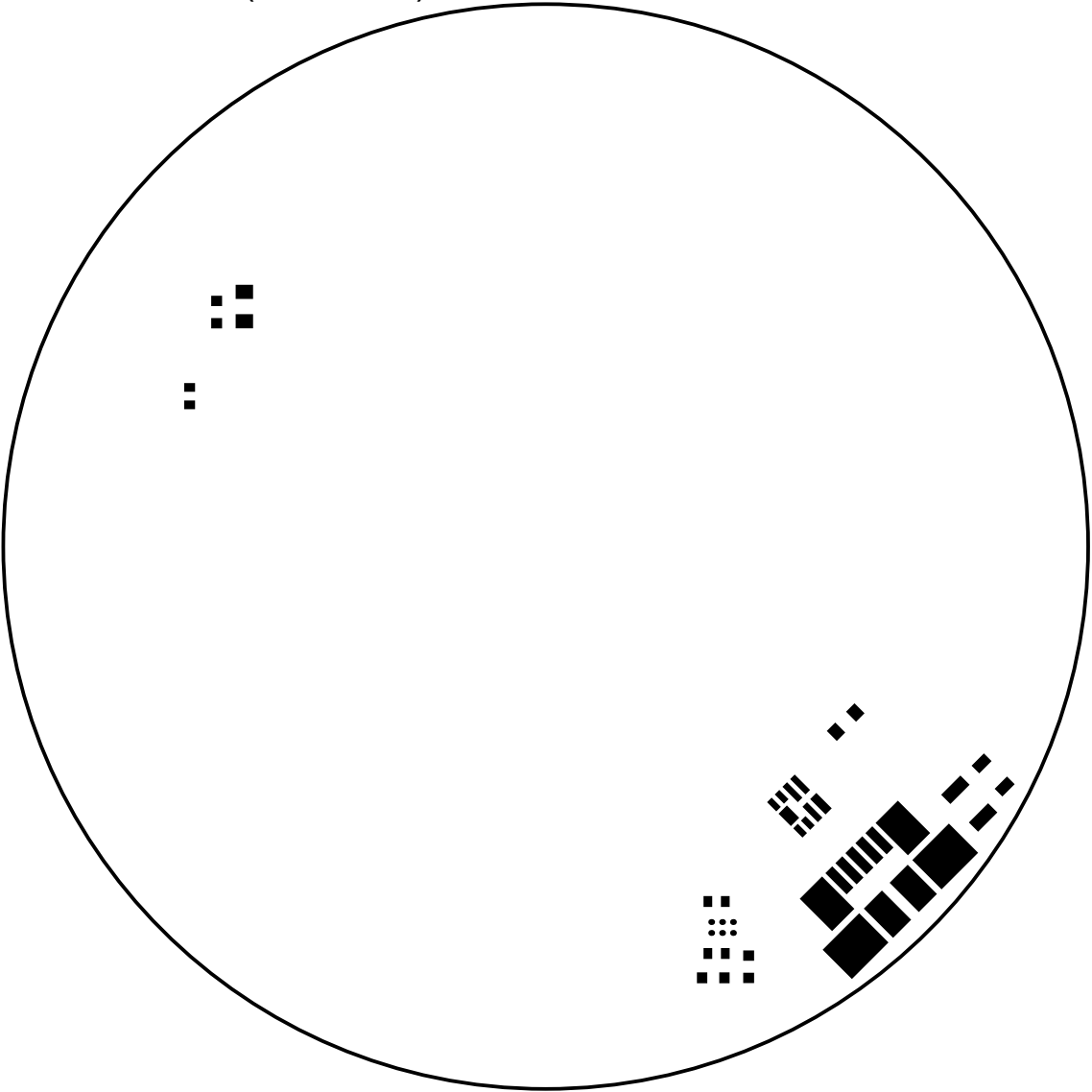
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Bottom Paste (Scale 3:1)



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Bottom side solder paste

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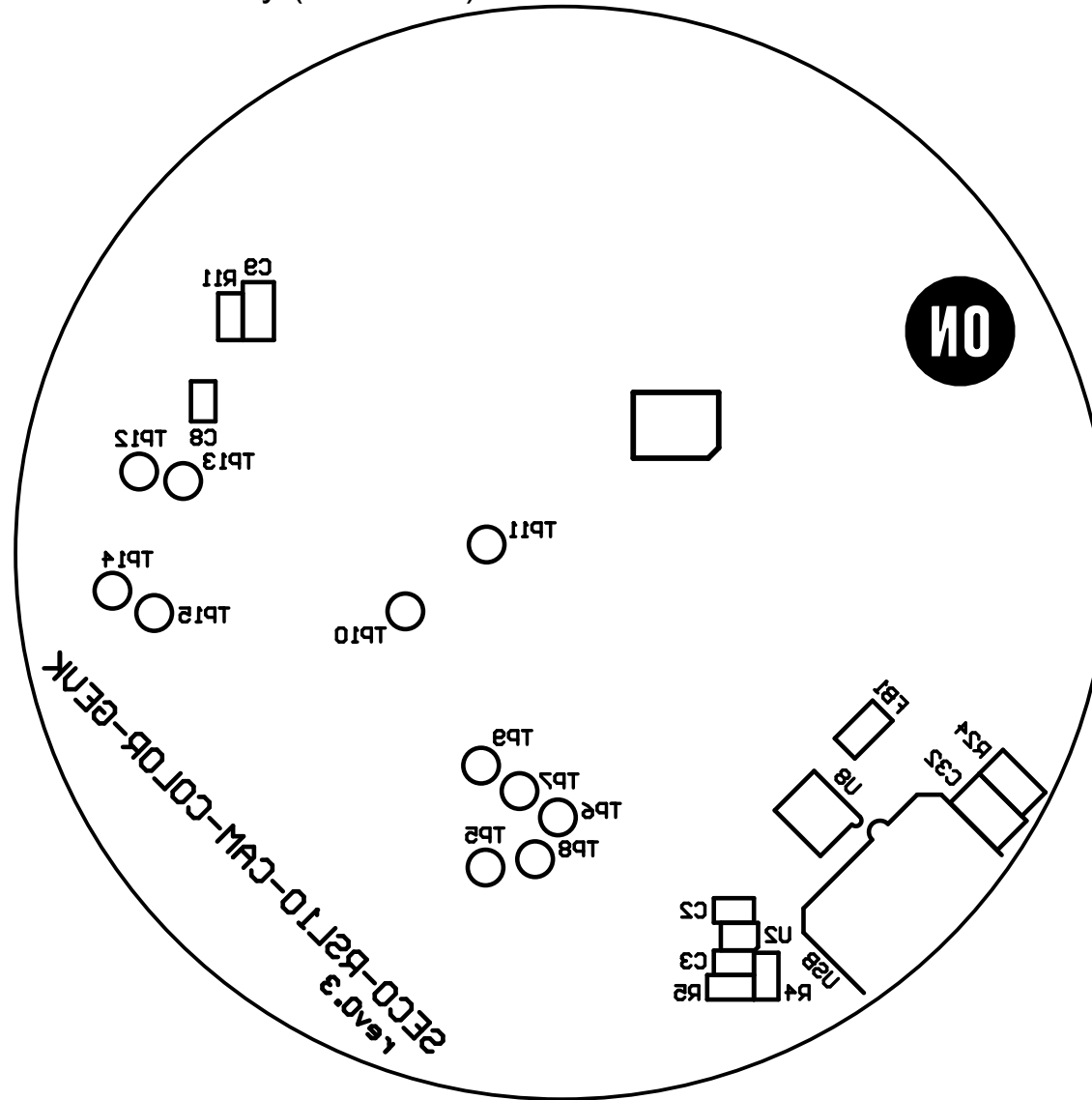
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Bottom Overlay (Scale 3:1)



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Bottom side silkscreen

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Drill Table - vias

Symbol	Count	Hole Size	Plated	Drill Layer Pair	Via / Pad	Template
⬢	11	0.125mm(5mil)	Plated	L1_TOP - L2_GND	Via	v8h4_t
⊗	27	0.152mm(6mil)	Plated	L1_TOP - L4_BOTTOM	Via	v12h6_t
⊕	10	0.152mm(6mil)	Plated	L1_TOP - L2_GND	Via	v12h6_t
◎	132	0.203mm(8mil)	Plated	L1_TOP - L4_BOTTOM	Via	v16h8_t
△	125	0.305mm(12mil)	Plated	L1_TOP - L4_BOTTOM	Via	v24h12_t
⊞	130	0.305mm(12mil)	Plated	L1_TOP - L4_BOTTOM	Via	v24h12
	435 Total					

Drill Table - pads

Symbol	Count	Hole Size	Plated	Drill Layer Pair	Via / Pad	Template
⊕	2	0.500mm(20mil)	Plated	L1_TOP - L4_BOTTOM	Pad	r300_200h50_120r100
⬢	1	0.500mm(20mil)	Plated	L1_TOP - L4_BOTTOM	Pad	r275_200h50_125r100
◇	3	0.600mm(24mil)	Plated	L1_TOP - L4_BOTTOM	Pad	c100h60
⊗	1	0.600mm(24mil)	Plated	L1_TOP - L4_BOTTOM	Pad	s100h60
☆	1	0.650mm(26mil)	Plated	L1_TOP - L4_BOTTOM	Pad	s145h65
⊗	2	0.650mm(26mil)	Plated	L1_TOP - L4_BOTTOM	Pad	c145h65
□	1	0.800mm(31mil)	Plated	L1_TOP - L4_BOTTOM	Pad	c130h80
○	1	0.800mm(31mil)	Plated	L1_TOP - L4_BOTTOM	Pad	s130h80m140
☆	3	1.016mm(40mil)	Non-Plated	L1_TOP - L4_BOTTOM	Pad	c102hn102
	15 Total					

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Drill tables

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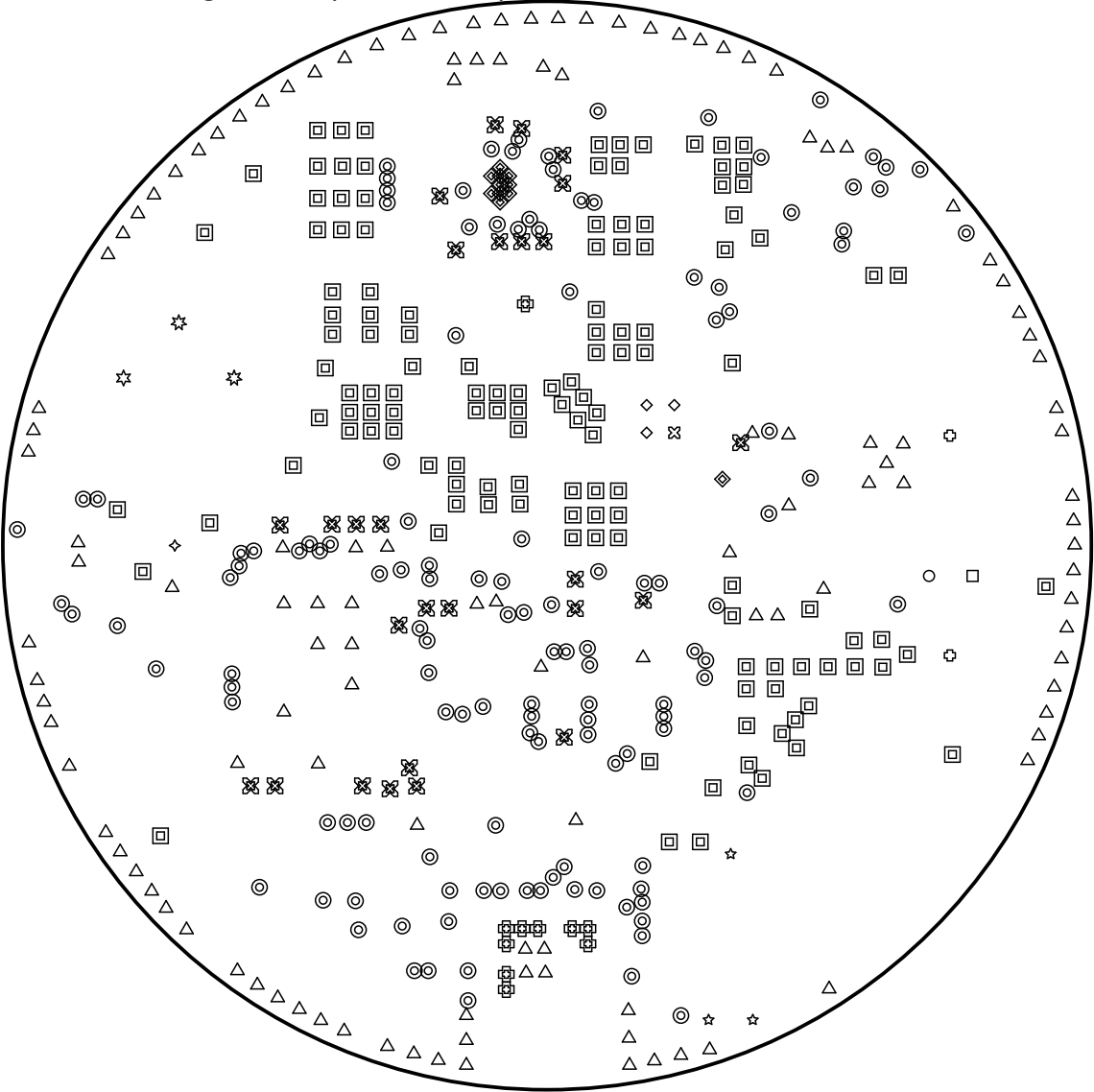
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Drill Drawing View (Scale 3:1)



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Drill drawing view

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